

The Valley Megaphone

Newsletter of the
**Institute of Electrical and
Electronics Engineers, Inc.,
Phoenix Section**
November, 2015
Volume XXIX, Number 11



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IEEE Phoenix Section on-line updates can be found at
<http://sites.ieee.org/phoenix/> and on LinkedIn
at:<http://www.linkedin.com/groups?gid=2765918>
and on Facebook at:
<https://www.facebook.com/IEEEPhoenixSection>

Please send announcements for the *Valley
Megaphone* to Wei Xu at Wei.Dr.Xu@ieee.org for
inclusion in the Section Calendar.

**All meetings announced in the
Phoenix Section Megaphone or on
the Phoenix Section Calendar are
open to everyone (IEEE members
and non-Members)**

Chapters

Signal Processing & Communications

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EMBS Chapter

TBD

EMC Society

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Power & Energy Society

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Solid State Circuits

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Teacher-In-Service

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Waves & Devices Society

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Life Members

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Women In Engineering

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Young Professionals

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U – News

(for Student Members)

Updates of Student Advisors and Committee Members

Each Student Branch noted on the right side of this page should review current information on Advisors and Student Committee Members and forward to my attention within this week, as we are reviewing contacts for reporting and activities including Student Monthly Meetings.

S. Diane Smith
602-749-4601
sdianesmith@computer.org
Student Activities Chair

Update from DeVry Phoenix-Engineering Student Branch

The IEEE Student Branch and Computer Society at DeVry University, Phoenix are co-sponsoring and co-managing with the University a Science Technology Engineering and Math (S.T.E.M.) exhibit at the 2015 Arizona State Fair. We have a 24 x 48 foot space that will house various high school and collegiate STEM projects often representing Capstone activities. In addition, four STEM workshops will be conducted by the students: Cyber Security (“Can You Hack It?”); personal computer repair (“DIY Computer Fixes”); beta-test student designed simulations (“Would you like to play a game?”); and breadboard kit building (“Make your own Night Light” and “Hidden Buzzer”). The static displays will be visible the duration of the Fair. The workshops are scheduled and published and will occur on the four weekends of the Fair. Section members and their families and friends are invited to stop by the exhibit and join us in the fun at the Arizona State Fair!

Roger S. Gulledge
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Student Branches

ASU Main, Engineering

Chair: Phoebe Henson
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ASU Main, Computer Society

Chair: TBD
Advisor: Guoliang Xue
480-965-6218, xue@asu.edu

ASU Polytechnic

Chair: Josh Carroll
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Elizabeth Long
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Advisor: : Dr. John M. Parsey, Jr.,
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DeVry, Phoenix – Engineering

Chair: Diego Hernandez
dhernan249@gmail.com
Advisor: Roger S. Gulledge
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DeVry, Phoenix – Computer Society

Chair: TBD
Past Chair: Zak Burgess
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602-749-4586
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Advisor: Deanna Davis
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NAU, Engineering

Chair: Jeremy Johnson
Advisor: Niranjan Venkatraman
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Embry-Riddle, Prescott

Chair: Lisa M. Ferguson
FERGUSL2@my.erau.edu
Advisor: John E. Post
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U – Newsbytes

ADVANCED MANUFACTURING SYSTEMS (11362)

The Ira A. Fulton Schools of Engineering at Arizona State University (ASU) is hiring faculty to support a broad initiative in advanced manufacturing. We are particularly interested in expanding our capabilities in the research areas that lie between the areas of basic research in the physics/materials/chemistry aspects of manufacturing processes and applied research at the production system and supply chain levels.

Specific areas of interest include, but are not limited to: multi-material manufacturing systems; hybrid additive-subtractive manufacturing process integration; scalable manufacturing at the limits of size, temperatures and material properties; product design strategies for additive manufacturing systems; non-destructive testing-manufacturing integration; automation strategies and technologies for hybrid manufacturing; modeling of advanced manufacturing systems and processes.

We seek applicants who will contribute to our academic programs, promote transdisciplinary teaching and research, and help the University to achieve its aspirations, including enabling student success, transforming society, valuing entrepreneurship, and conducting use-inspired research.

Faculty members are expected to develop an internationally recognized and externally funded research program, adopt effective pedagogical practices in the development and delivery of graduate and undergraduate courses, advise both undergraduate and graduate student research and projects, and undertake service activities.

Required qualifications:

Required qualifications include an earned doctorate in Manufacturing Engineering, Materials Science and Engineering, Mechanical Engineering, Industrial Engineering, or a related field, along with demonstrated evidence of research and teaching excellence as appropriate to the candidate's rank.

Desired qualifications:

Desired qualifications include a demonstrated commitment to a collaborative approach to research and the use of modern pedagogical practices in teaching.

Appointment will be at the **Assistant, Associate, or Full Professor** rank commensurate with the candidate's experience and accomplishments, beginning August 2016.

While the faculty appointment may be in any of the six Fulton Schools of Engineering, The Polytechnic School, located at ASU's Polytechnic campus in Mesa, Arizona, is currently the most involved in the search. The Polytechnic School offers related degrees at the bachelor's level in Engineering and Manufacturing Engineering, at the master's level in Engineering, and at the Ph.D. level in Systems Engineering. Additionally, the Polytechnic School houses the premier additive manufacturing and research center in the Southwest, providing strong support for the advancing ASU's research and development in Advanced Manufacturing. The facility features over \$2M in state-of-the-art polymer, metal, and composite materials 3D printing equipment as well as advanced materials processing and analysis capabilities.

How to apply:

To apply, please submit a single PDF file to advanced.manufacturing.faculty@asu.edu that includes:

- Cover letter.
- Current CV.
- Statement describing research interests (two pages maximum).
- Statement describing teaching interests and philosophy (two pages maximum).
- Contact information for three references.

Review of applications will begin November 16, 2015; if not filled, reviews will occur on the 1st and 15th of the month thereafter until the search is closed.

For more information or questions about these positions, please contact the search committee chair, Jennifer Bekki (jennifer.bekki@asu.edu).

Arizona State University is a VEVRAA Federal Contractor and an Equal Opportunity/Affirmative Action Employer. All qualified applicants will be considered without regard to race, color, sex, religion, national origin, disability, protected veteran status, or any other basis protected by law. See ASU's full [non-discrimination statement](#) (ACD 401) at [_](#) and the [Title IX statement](#).

ASU offers applicants an opportunity to voluntarily disclose information for the University's affirmative action plan; applicants may complete an [EEO survey](#) for the position they are applying for online.

Information you'll need to complete the survey:

Job Number: 11362

Job Title: POLY Advanced Manufacturing

Department Name: Engineering

Update from DeVry Phoenix-Engineering Student Branch

The DeVry University IEEE Student Branch was very fortunate to construct a S.T.E.M exhibit at the 2015 Arizona State Fair. We had a variety of S.T.E.M displays, and multiple workshops for fairgoers to participate in. The Student branch has been all hands on deck with this assignment throughout the final weeks of October and the first week of November; volunteering to run workshops in the following areas: PC Maintenance & Repair, Game-simulation Programming, Hack-a-thon, Cyber security for the home user, and Basic Electronic circuit builds. We reached out to hundreds of people over the course of the fair and instilled a growing interest in S.T.E.M. Planning ahead; we are starting discussions on our participation in the SkillsUSA event next March. Our IEEE Student Branch will be in charge of the Engineering Technology Competition and our IEEE Computer Society will be in charge of the Information Technology Services Competition. On a final note, our IEEE Student Branch welcomed along Oscar Jaquez as our new vice chair.

Diego Hernandez
Chair, IEEE DeVry Student Branch
Dhernan249@gmail.com

Update from Embry-Riddle Student Branch

October update for the Embry-Riddle Aeronautical University IEEE chapter in Prescott, Arizona. This past month the IEEE chapter at ERAU had three students participate in the IEEE X-Treme challenge held on the 24th of October. The chapter also had Dr. Siewert speak about multispectral cameras at the monthly meeting on the 26th of October. Dr. Siewert gave a presentation about his joint project research with the University of Alaska Anchorage, University of Colorado- Boulder and the Department of Homeland Security. Dr. Siewert explained how thermal imaging cameras operate and possible future uses and research to the twenty students that attended the meeting.



Upcoming Conferences in Region 6

Hello IEEE Student Members!

[2015 IEEE Workshop on Automatic Speech Recognition and Understanding \(ASRU\)](#) will be held Dec 13 to 16, 2015

[The second annual IEEE Rising Stars Conference](#) will be held in Las Vegas, Nevada at the Excalibur Hotel & Casino on January 2-4, 2016

[2016 IEEE 66th Electronic Components and Technology Conference \(ECTC\)](#) will be held on May 28-Jun 5, 2016

[2016 15th IEEE Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems \(ITherm\)](#) will be held on May 31 – Jun 3, 2016

[2016 IEEE International Conference on Image Processing \(IEEE ICIP\)](#) will be held at the Phoenix Convention Center, Phoenix, AZ on September 25-28, 2016.

Recognizing Our Members

by Tom Coughlin, Region 6 Director

One of the best ways to retain IEEE members is to recognize them for their service to society and the profession. IEEE members who are elevated to senior membership are much more likely to remain IEEE members for an extended period.

The IEEE Senior membership recognizes members for their contribution to society and to the profession over a long period of time. Many IEEE members qualify for this recognition (they have 10 or more years of useful activity and/or contribution to the profession) but a minority of these folks so qualified, are actually senior members.

Earlier this year I was involved in elevating Steve Wozniak (the Woz) to be a senior member—you would be surprised to find out who isn't yet a senior member. If you aren't a senior member yet, you are the majority of members, but you can be a senior member and receive benefits from this status.

One of the best things that we can do for fellow members of our IEEE community is to recognize them for their efforts and achievements. For this reason we need to do more to help members that qualify become senior members. The goal for IEEE Region 6 is 340 senior member advancements in 2015 and we have reached 74% of that goal. How can we increase the number of senior member elevations in our region? First, review the senior member information on the web site at:

http://www.ieee.org/membership_services/membership/senior/index.html

If you or someone you knows meets these qualifications submit them to be a senior member. Note the big issue is that 3 IEEE senior members or fellows need to provide the nomination or recommendations to have a valid senior member submission. Getting 3 senior members or fellows to be part of the submission is usually the biggest issue.

Sections can help with these elevations by organizing events bringing together senior members and fellow and senior member candidates to sit together and fill in the on-line forms to submit people to be senior members. It is amazing how many of these can be done in an hour or two with a number of senior members connected to the internet. These sort of Senior Member Rodeos or Round Ups can really help to increase the number of senior members. In addition Sections can keep a list of senior members that potential candidates can contact to submit for senior members.

In addition to senior member elevations each section probably has a number of members who are “associate” members. These people pay the same membership fees as full members but they are not able to vote in IEEE elections, serve IEEE volunteer offices and are not recognized as full members. Most of these associate members are eligible to be full members but unless someone investigates and starts this process they will remain as associate members. Elevating someone from an associate to a full IEEE member is a much simpler process than a senior member elevation and all sections should contact their associate members and see if they can be made full members.

Let's help our fellow members get recognized for their experience and talents. As a community we need to help each other and recognize our good efforts and successes. If you are a senior member, IEEE fellow or section officer please help your fellow members become senior members.

Recording Technical Meetings

by Tom Coughlin, Region 6 Director

Going further along the lines of what we can do for each other, I urge you to look at and contribute to our technical chapter-recording project. This is an IEEE NIC funded activity that is going between IEEE Region 4 and 6 this year to train and equip our section chapter leaders to capture their technical chapter meetings and submit them to a web site where these can be viewed for free by IEEE members.

With this capability technical chapter meetings can be shared with IEEE members all over the world and if you happen to miss an interesting meeting you can still listen to what was presented.

We urge you to get your local chapters involved in recording their meetings. You can find more information on this on the Region 6 web site under 2015 Opcom meeting at:

<http://ieee-region6.org/category/region-meetings/>

and also from the chapter recording viewing and access site at: <http://www.nuxlabs.com> where you can create an account and view, search and comment on existing recordings as well.

If you are ready to start recording in your section chapters please contact Scott Tamashiro <tamashiro@ieee.org> who can get you the latest material and also help you with resources such as a microphone set and Techsmith Camtasia software that you can use to start recording your chapter technical meetings.



IEEE PHOENIX SECTION



Annual Banquet - Saturday, February 13th, 2016

Hilton Phoenix Airport, 2435 South 47th Street, Phoenix, Arizona 85034

Keynote Presentation

Title: Are there plenty more fish in the sea?

Speaker: Dr. David A. Demer

Senior Scientist and Leader, Advanced Survey Technologies Program
National Oceanic and Atmospheric Administration
8901 La Jolla Shores Drive
La Jolla, CA, 92037

Abstract

Most people are consuming more fish and are paying more for it. Less of it is wild caught and more is from aquaculture. Wild fish populations depend on ecosystem productivity, which is effected by a variety of forces such as El Niño, the Pacific Decadal Oscillation, climate change, ocean acidification, pollution, and fishing. These factors can change fish distributions, damage habitats, and alter biodiversity and ecological functions. In this context, we will explore the living resources in two of the most productive ecosystems on Earth: the Scotia Sea in the Southern Ocean, off the Antarctic Peninsula; and the California Current off the west coast of North America. We will learn how a variety of optical and acoustic instruments, and manned and autonomous vehicles are used to probe these remote and often inaccessible regions. In the process of counting and mapping exploited fish, we will touch on the complex interactions of climate, weather, seabed and oceanographic environments, avian and marine prey and predators, and fishers. We may enhance our appreciation for the effect the world ocean has on humanity, and vice-versa.

Speaker Biography



Dr. David A. Demer earned a B.S. in Electrical and Computer Engineering (ECE) from University of Arizona in 1986, worked as a Product Engineer for Intel Corporation from 1986 to 1989, received a Hertz Foundation Fellowship in 1989, and was awarded a Ph.D. in Applied Ocean Science / ECE from Scripps Institution of Oceanography (SIO), University of California at San Diego in 1994. He began his career with the National Oceanic and Atmospheric Administration at the Southwest Fisheries Science Center (SWFSC) as a Research Engineer with the Antarctic Ecosystems Research Division in 1990. He became the Leader of SWFSC's Advanced Survey Technologies Program (AST) in 1999, a Research Associate with the Marine Physical Laboratory at SIO in 2000, a Research Associate with the Integrative Oceanography Division at SIO in 2007, Guest Editor for the ICES Journal of Marine Science (JMS) in 2009, Review Editor for the JMS in 2012, and Senior Scientist at the SWFSC in 2010. Presently, he continues to lead the AST, acoustic-trawl surveys of fish and zooplankton, and the development and application of new marine and riverine sampling instruments and techniques. Over the last 25 years, Dr. Demer has designed and conducted investigations of zooplankton and fish stocks, predator-prey interactions, and ecosystems along the west coast of North America from the Sea of Cortes to the Bering Sea; along the east coast from the Gulf of Mexico to the Gulf of Maine; in the Irish, Ligurian, and Red Seas, off South Africa, and in the Southern Ocean.



IEEE PHOENIX SECTION



Annual Banquet - Saturday, February 13th, 2016

Hilton Phoenix Airport, 2435 South 47th Street, Phoenix, Arizona 85034

Banquet Agenda

Registration / Social Hour:	5:30 PM – 6:30 PM
Sit-Down Dinner:	6:30 PM – 7:15 PM
Section Program:	7:15 PM – 8:00 PM
Keynote Presentation:	8:00 PM – 8:30 PM
Awards Presentation:	8:30 PM – 9:15 PM
Change of Section Officers:	9:15 PM – 9:30 PM

Business Attire is recommended

Banquet Web Links

Complete Banquet Information along with Banquet Registration: <http://sites.ieee.org/phoenix/>

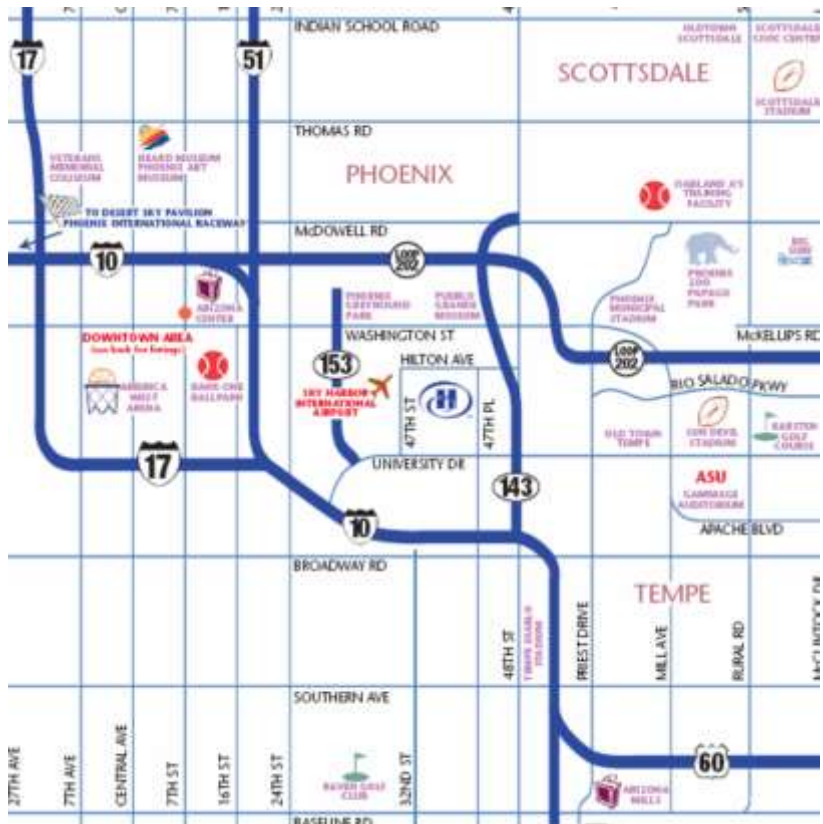
Banquet Registration Direct Link: <https://meetings.vtools.ieee.org/m/36447>

Banquet Venue



2435 South 47th Street
Phoenix, Arizona 85034
(480) 894-1600

West of Hohokam (143) Freeway and
North of University Drive



IEEE Phoenix Section Information

Please Support the IEEE Phoenix Section by Joining as Volunteer in Section Committees, Society Chapters, Affinity Groups, and Student Branches

IEEE Phoenix Section Executive Meeting on First Tuesday of the Month at Hilton Phoenix Airport

IEEE Phoenix Section Executive Committee Meeting is Open to Section Members

Visit the Section website at sites.ieee.org/phoenix/ for additional information

2015 Phoenix Tech-Security Conference

Place: Phoenix Marriott Mesa
200 North Centennial Way
Mesa, Arizona 85201

Date: Thursday, November 19th, 2015
8:15am-5:00pm

Click on the following link to register for your *free VIP pass*:
<http://phoenixtechsecurity2015.eventbrite.com/?aff=np>

- VIP passes include Breakfast, Lunch, Conference materials and Entrance into conference sessions and exhibit areas.
- This conference qualifies for CPE credits and Certificates of Attendance.
- Gift Cards, iPads, Kindles and many other door prizes and give aways.
- Featuring (11) IT Security speakers and over 30 exhibits!!

For full conference agenda click on:

<http://dataconnectors.com/upcoming-events-and-agendas/15-phoenix-tech-security-conference-2015>

or call Stephanie Lange at [636-778-9495](tel:636-778-9495) for more information.

slange@DataConnectors.com

To join our mailing list, click on:

<http://dataconnectors.com/mailling-list-signup>



**Where Students and Young Professionals
Come to Connect and be Inspired**

**THE PREMIERE EVENT IN THE
WESTERN UNITED STATES!**

The IEEE Region 6 Rising Stars Conference is designed to Inform, Excite, Enthuse, and Enlighten the top engineering students and young professionals of IEEE. The program includes interactive events, introductions to new technical innovations, networking opportunities, and professional development.

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- IEEE STUDENT MEMBER | \$199
- IEEE MEMBER | \$349
- Non-IEEE MEMBER | \$449
- Special 1 day Storage Visions Registration

JANUARY 2 – 4, 2016

EXCALIBUR HOTEL

LAS VEGAS, NV

HELD IN CONJUNCTION WITH THE
STORAGE VISIONS CONFERENCE
AND THE
**CONSUMER ELECTRONICS SHOW
(CES)**

SPEAKERS:

- ★ Jamie Garcia, IBM
- ★ Karen Panetta, Dean of Tufts University
- ★ Kate Jenkins, Ejenta, Inc.
- ★ Monica Giffin, Raytheon
- ★ Tiffany Finley, Southwest Research Institute
- ★ Joey Yang, Google
- ★ Patrick Griffins, Dolby
- ★ whurley (William Hurley), Happy Dollar
- ★ Michelle Yung, Orbital ATK
- ★ Karen Bartleson, Synopsys

TOPICS:

SPACE TECHNOLOGY
NINJA POLYMERS
INTERNET OF THINGS
WEARABLE DEVICES
ENTERTAINMENT TECHNOLOGY
POWER SYSTEMS AND STORAGE
CLOUD COMPUTING
UNLEASHING YOUR INNER ENTREPRENEUR
PROFESSIONAL NETWORKING
MARKETING AND SELLING YOURSELF

WANT TO REACH THE BEST AND THE BRIGHTEST YOUNG ENGINEERS?

PARTICIPATE AS A CORPORATE SPONSOR!

2016 IEEE International Conference on Image Processing (IEEE ICIP)

Phoenix Convention Center, Phoenix, AZ,

25-28 September 2016.

Website: 2016.ieeeicip.org

IEEE ICIP 2016 is the event for researchers, developers, product creators, educators and students who want to share, learn about, and advance the state-of-the-art in the areas of image/video processing, image/video communications, computer vision, computational imaging, and visual technologies based applications.

IEEE ICIP attendees include more than 1000 experienced researchers/developers including educators, engineers, computer scientists, and students, providing great networking and recruiting opportunities.

Important Dates:

Special Session and Tutorial Proposals: November 16, 2015

Paper Submissions: January 25, 2016

Visual Technology Innovation Award Nomination: March 31, 2016

Visual Technology Showcase Submission: May 15, 2016

IEEE ICIP 2016 highlights:

- nominate an individual or team for the Visual Innovation Award by 31 March 2016: This Award was created to recognize pioneers of transformative technologies and business models in areas within the technical scope of IEEE ICIP. The Award showcases innovations that have had great impact on human experiences with technology or are anticipated to do so in the near future. The Award Committee consists of well-known industry executives, visionary entrepreneurs, and scholars.
- maximize the visibility of your work via free open preview: Papers accepted to ICIP 2016 will (upon author approval) be available in their final accepted format on IEEE Xplore, freely accessible and downloadable by all in their final format from Aug 20, 2016 through September 30, 2016.
- maximize your networking and career connections: attendees will be given the opportunity to upload their CVs to be shared among interested recruiters for full-time, part-time, and consulting job opportunities. These CVs will be made available through a password-protected searchable platform to ICIP 2016 supporters/recruiters.
- experience state-of-the-art visual technology products and prototypes at the ICIP'16 Visual Technology Showcase. IEEE ICIP 2016 will feature a Visual Technology Showcase where technology creators and developers can present live demos of recent visual technologies and prototypes. *Participants who are interested in demoing their technology should submit a description of the technology at the IEEE ICIP 2016 website by 15 May 2016.*
- attend presentations, tutorials, and training courses by experts in the areas of image/video processing, image/video compression, computer vision, computational imaging, biomedical imaging, and other topics within the scope of IEEE ICIP 2016.



General Chair
Lina Karam
 Arizona State University

Vice-General Chair
Aggelos Katsaggelos
 Northwestern University

Technical Program Chairs
Fernando Pereira
 Instituto Superior Técnico

Gaurav Sharma
 University of Rochester

Innovation Program Chairs
Haohong Wang
 TCL Research America

Jeff Bier
 BDTI & Embedded Vision Alliance

Khaled El-Maleh
 Qualcomm Technologies Inc.

Finance Chair
Sohail Dianat
 Rochester Institute of Technology

Plenary Chairs
Michael Marcellin
 University of Arizona

Sethuraman Panchanathan
 Arizona State University

Special Sessions Chairs
Dinei Florencio
 Microsoft Research

Chaker Larabi
 Poitiers University

Zhou Wang
 University of Waterloo

Challenge Sessions Chair
Dinei Florencio
 Microsoft Research

Tutorials Chairs
Ghassan AlRegib
 Georgia Tech

Rony Ferzli
 Intel

Publicity Chair
Michel Sarkis
 Qualcomm Technologies Inc.

Paper Awards Chairs
Vivek Goyal
 Boston University

Ivana Tosic
 Ricoh Innovations

Exhibits Chair
David Frakes
 Arizona State University & Google

Publication Chairs
Patrick Le Callet
 Nantes University

Baoxin Li
 Arizona State University

Local Arrangement Chair
Pavan Turaga
 Arizona State University

Registration Chair
Ricardo De Queiroz
 Universidade de Brasilia

The 23rd IEEE International Conference on Image Processing (ICIP) will be held in the Phoenix Convention Centre, Phoenix, Arizona, USA, on September 25 - 28, 2016. ICIP is the world's largest and most comprehensive technical conference focused on image and video processing and computer vision. In addition to the Technical Program, ICIP 2016 will feature an Innovation Program focused on vision technologies and fostering innovation and networking. The conference will feature world-class speakers, tutorials, exhibits, and a vision technology showcase.

Topics in the ICIP 2016 Technical Program include but are not limited to:

<i>Filtering, Transforms, Multi-Resolution Processing</i>	<i>Video Processing and Analytics</i>
<i>Restoration, Enhancement, Super-Resolution</i>	<i>Authentication and Biometrics</i>
<i>Computer Vision Algorithms and Technologies</i>	<i>Biological and Perceptual-based Processing</i>
<i>Compression, Transmission, Storage, Retrieval</i>	<i>Visual Quality Assessment</i>
<i>Computational Imaging</i>	<i>Scanning, Display, and Printing</i>
<i>Color and Multispectral Processing</i>	<i>Document and Synthetic Visual Processing</i>
<i>Multi-View and Stereoscopic Processing</i>	<i>Applications to various fields</i>
<i>Multi-Temporal and Spatio-Temporal Processing</i>	

New initiatives at ICIP 2016 include:

- 1) Open preview for accepted papers on IEEE Xplore;
- 2) Visual Innovation Award (individual or team nominations due by 31 March 2016 at conference website);
- 3) Support for reproducible research;
- 4) Support for CV uploads on the ICIP site for full-time, part-time, and consulting job opportunities;
- 5) Visual Technology Showcase (submission due by 15 May 2016). For more details on these and other new initiatives at ICIP 2016, visit 2016.ieeeicip.org and connect now on the ICIP 2016 social media to get automatic updates about the various deadlines, sessions and events.

Paper Submission:

Prospective authors are invited to submit full-length papers at the conference website, with up to four pages for technical content including figures and references, and with one additional optional 5th page for references only. Submission Instructions, templates for the required paper format, and information on "no show" policy are available at 2016.ieeeicip.org.

Tutorials, Special Sessions, and Challenge Sessions Proposals:

Tutorials will be held on September 25, 2016. Tutorial proposals should be submitted at the conference website and must include title, outline, contact information, biography and selected publications for the presenter(s), and a description of the tutorial and material to be distributed to participants. For detailed submission guidelines, please refer to the tutorial proposals page. Special Sessions and Challenge Session Proposals should be submitted at conference website and must include a topical title, rationale, session outline, contact information, and a list of invited papers/participants. For detailed submission guidelines, please refer the ICIP 2016 website at 2016.ieeeicip.org.

Important Deadlines:

- Challenge Session Proposals: October 30, 2015
- Special Session and Tutorial Proposals: November 16, 2015
- Notification of Special Session and Tutorial Acceptance: December 18, 2015
- Paper Submissions: January 25, 2016
- Notification of Paper Acceptance: April 30, 2016
- Visual Innovation Award Nomination: March 31, 2016
- Visual Technology Showcase Submission: May 15, 2016
- Notification of Visual Technology Showcase Acceptance: May 30, 2016
- Revised Paper Upload Deadline: May 15, 2016
- Authors' Registration Deadline: May 15, 2016



World's FIRST

Visual Innovation Award

Call for Nomination: The Award recognizes pioneers of transformative technologies and business models that have had great impact on human experiences or are anticipated to do so in the near future. The Award Committee consists of well-known industrial executives, visionary entrepreneurs, and scholars. Nominations are to be submitted online no later than 31 March 2016. The nominations will be forwarded to the Award Committee for selection of finalists who will be presented with their award at IEEE ICIP 2016. Please visit 2016.ieeeicip.org for more information and for the online submission form.

Nominate your favorite visual innovation TODAY! Details can be found at <http://2016.ieeeicip.org/VisualInnovationAward.asp>

Important Dates:

31 March 2016: Deadline for nominations

15 June 2016: Finalists announced

Award Committee



Giles Baker
SVP
Dolby Labs



Nikhil Bairam
CEO
Ricoh Innovations



Hanno Basse
CTO
20th Century Fox



Achin Bhowmik
VP
Intel



James Brallean
Managing Partner
Karmel Capital



Bill Dally
SVP
nVidia



Robert Gove
VP
Synaptics



Hsiao-Wuan Hsu
Chairman of ARD
Microsoft



Kevin Jou
CTO
MediaTek



C C Lee
SVP
Sony



Matthew Mengerink
VP
Google



Anthony Park
VP
Netflix



Raj Talluri
SVP
Qualcomm



Martin Vetterli
President
Swiss NSF NRC



Susie Wee
CTO
Cisco



Lina Karam
Professor
Arizona State



Aggelos Katsaggelos
Professor
Northwestern



Haohong Wang
General Manager
TCL



Khaled El-Maleh
Sr. Director
Qualcomm



Jeff Bier
President, Embedded
Vision Alliance



2016.ieeeicip.org




IEEE

THE INSTITUTE OF ELECTRICAL AND ELECTRONICS ENGINEERS, INC.


 IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY

IEEE Components, Packaging and Manufacturing Technology Society Phoenix Chapter

2015 Executive Committee for CPMT Chapter for IEEE-Phoenix Section

Position	Name	Phone Contact	Email Contact
Chair	Dr. Mahesh K. Shah	(480) 544-9438	mkshah@ieee.org
Asst. Chair	Mr. Vivek Gupta	(480) 734-2366	vmgupta@msn.com
Secretary	Dr. Rao Bonda	(480) 786-7749	r.bonda@ieee.org
Treasurer	Dr. Vasudeva P. Atluri	(480) 227-8411	vpatluri@ieee.org
Program Chair	Mr. David Dougherty	(480) 245-8099	david.dougherty@freescale.com
Asst. Program Chair			
Tutorial Chair	Dr. Shawn Shi	480-929-5614	Songhua.Shi.2011@ieee.org
Asst. Tutorial Chair			
Workshop Chair & Publicity	Dr. Vasudeva P. Atluri	(480) 227-8411	vpatluri@ieee.org
Website Co-Chair	Bharat Penmecha	(480) 552 2511	bharat.penmecha@ieee.org
Website Co-Chair	Huiyang Fei		Huiyang.H.Fei@ieee.org

Tentative Schedule for Monthly Seminars

Date	Topic	Speaker
Feb. 18, 2015	Packaging & Failure Analysis Challenges in Advance 3D packages	Dr. Deepak Goyal
Mar. 18, 2015	High Spatial Resolution Strain Mapping in TEM using Precession Electron Diffraction	Dr. Amith Darbal
April 22, 2015	Seminar Cancelled	
May	No Seminar due to IMS-2015 in Phoenix	
June 17, 2015	Materials Characterization: A Model for Open Access	Leroy Eyring Center, ASU
July 22, 2015	In Preparation for Retirement: Plan Early and Plan Often!	Gregory Wojak
August	No seminar for August	
September 23, 2015	HDI Routing & Construction Design Strategies From 1.27 mm to 0.4 mm	Terry Regan, TTM Technologies
October 21st, 2015	Details to be Announced Later	Dr. Hans Stork, CTO ON Semiconductor
November 18, 2015	Film Assisted Molding	John Crane, Boschman Technologies
December 9th, 2015	Heterogeneous Integration of Microdevices by Micro-Transfer Printing	Dr. Christopher Bower, CTO, X-Celeprint Ltd.
January 20 th , 2015	Understanding and Managing the Key Cost drivers in PCB design to optimize performance and Cost	Marc Licciardi, Founder DFX Engineering
February 27 th , 2016	Details to be Announced Later	Dr. Bill Bottoms



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THE INSTITUTE OF ELECTRICAL AND ELECTRONICS ENGINEERS, INC.



IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY

IEEE Phoenix Section – CPMT Society Chapter Nomination of Officers

The IEEE Phoenix Section, CPMT Society Chapter is seeking nominations for the following elected Section officer positions for the 2016 term:

- Chair
- Asst. Chair
- Secretary
- Treasurer

Additionally, the Nominating Committee is seeking candidates for some of the following non-elected appointed standing committee Chair positions for the 2016 term:

- Program Chair
- Tutorial Chair
- Workshop Chair
- Publicity
- Web Master

Society officers must be IEEE and CPMT members. Self-nominations are acceptable.

Please send nominations or any questions to any member of the Nomination Committee via an email.

Dr. Mahesh Shah (Current Chair): mkshah@ieee.org

Dr. Vasudeva Atluri (Past Chair): vpatluri@ieee.org

Deadline for Nominations is December 11, 2015.



THE INSTITUTE OF ELECTRICAL AND ELECTRONICS ENGINEERS, INC.



IEEE COMPONENTS, PACKAGING AND MANUFACTURING TECHNOLOGY SOCIETY

IEEE Components, Packaging and Manufacturing Technology Society Phoenix Chapter

Wednesday, November 18th, 2015 at 5:30 PM

Film Assisted Molding: An Enabling Technology for Encapsulation of Advanced Packages

John Crane

JH Crane & Associates

Scottsdale, AZ 85266 USA

jhcrane@earthlink.net

ABSTRACT

The use of film in the transfer molding process, called Film Assist Molding (FAM), enables repeatable and high volume packaging for surfaces that must be kept free of mold compound, such as for Sensor/MEMS applications. Moreover, this encapsulation technology has provided the pathway for ever-increasing complex packages that are smaller and thinner, while compatible with superior mold compounds to meet the most stringent, cost effective customer device and package performance requirements. This presentation will introduce FAM, explore the possibilities and benefits of FAM to semiconductor encapsulation and explore implemented FAM solutions showing that it is possible to economically manufacture advanced packages of Sensors and MEMS in high volume production while achieving high device reliability.

BIOGRAPHY

John Crane is the Boschman Technologies and Advanced Packaging Center North America Sales Representative. His firm, JH Crane & Associates, has represented suppliers of semiconductor packaging equipment and materials for more than 21 years.

John earned a BS degree in Mathematics from Villanova University in 1978 and a MS degree in Systems Management from the University of Southern California in 1985. After serving seven years as a nuclear submarine officer, he entered the electronics field. John is currently the vice mayor of Carefree, AZ.

Boschman Technologies is a leading supplier of automatic transfer molding systems that use film for the encapsulation of Sensor and MEMS devices. This process, called Film Assist Molding, is ideal for applications where sensing surfaces or bond pads or heat sinks must be exposed and free of mold compound bleed and flash. Advanced Packaging Center offers research, development, qualification, prototyping and small volume production services focusing on MEMS, Sensor and advanced IC and wafer level packaging realized through Film Assist Molding.

Date: Wednesday, October 21st, 2015
Location: Group Conference Room, Freescale Semiconductor, Inc., Discovery Business Center, 2100 E. Elliot Rd. Tempe, AZ. Enter the facility through the Main (South) Lobby in building 94 and sign in with Security (Photo ID required) **BEFORE 6:00 PM**. You will be escorted to the meeting room. The presentation promptly starts at **6:00 PM**.
Agenda: 5:30–6:00 PM: Social/Refreshments, 6:00–7:00 PM: Presentation, 7:00 PM: Dinner (Pizza and Soda will be provided by the IEEE Phoenix Section CPMT Society Chapter)
IEEE members and non-members are all welcome to attend. **Please arrive at the facility entrance no later than 5:45 PM.**

For more information, please contact any of the following CPMT officers:

Vasu Atluri	(480) 227-8411	Rao Bonda	(480) 786-7749	David Dougherty	(480) 413-6923
Vivek Gupta	(480) 734-0266	Bharat Penmecha	(480) 552-2511	Mahesh Shah	(480) 544-9438
Shawn Shi	(480) 929-5614	Huiyang Fei	(480) 552-4966		



THE INSTITUTE OF ELECTRICAL AND ELECTRONICS ENGINEERS, INC.



IEEE COMPONENTS, PACKAGING AND MANUFACTURING TECHNOLOGY SOCIETY

IEEE Components, Packaging and Manufacturing Technology Society Phoenix Chapter

Monday, December 14th, 2015 at 5:30 PM

Heterogeneous Integration of Microdevices by Micro-Transfer Printing

Dr. Christopher (Chris) A. Bower

Chief Technology Officer

X-Celeprint

3021 Cornwallis Rd., Research Triangle Park, North Carolina, USA

cbower@x-celeprint.com

ABSTRACT

Micro-Transfer-Printing is a broadly applicable and practical micro assembly technology that was originally conceived and developed at the University of Illinois over a decade ago. In Micro-Transfer-Printing, an elastomeric stamp is used to transfer devices from their native semiconductor wafer onto non-native substrates such as glass, plastics, ceramics or other semiconductors. The transfer process relies on reversible, differential, and/or switchable adhesion to manipulate arrays of many small and fragile devices. The elastomer stamp based transfer process is deterministic, accurate, occurs at room temperature and requires no liquids or solvents.

In this work, we will present results from recent development programs aimed at using Micro-Transfer-Printing to heterogeneously integrate microscale compound semiconductor devices. We will describe the processes used to make a diversity of printable microscale devices, including devices made from Gallium Arsenide, Gallium Nitride and Indium Phosphide. The devices presented are typically thin, generally less than 10 microns, and have lateral dimensions less than 100 microns. We will show Micro-Transfer-Printing process yields and accuracy for a variety of device classes, including LEDs, lasers and transistors. The work will include an analysis of the process throughput and cost effectiveness in a variety of applications. Finally, we will discuss some emerging applications that are expected to leverage micro assembled compound semiconductors.

BIOGRAPHY



Dr. Christopher (Chris) A. Bower is the Chief Technology Officer at X-Celeprint Limited, a company founded to develop and commercialize advanced micro assembly technologies. He was formerly a Technical Manager at Sempruis, Inc., where he led the team responsible for micro-transfer-printing and wafer-level packaging of advanced microscale solar cells.

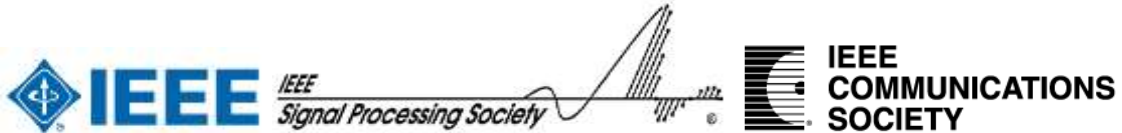
His past experience includes three years of research and development on three-dimensionally integrated circuits at RTI International and four years of research on nanotechnology and photonics devices at Bell Labs and InPlane Photonics, Inc. Chris received a Ph.D. degree in physics from the University of North Carolina, Chapel Hill, in

2000, where his graduate studies focused on the synthesis and novel properties of carbon nanotubes. His interests include three dimensional integration of integrated circuits, heterogeneous integration of compound semiconductors onto non-native substrates and the fabrication of low-cost, large-format electronics using novel assembly methods.

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- Date:** Wednesday, October 21st, 2015
Location: Group Conference Room, Freescale Semiconductor, Inc., Discovery Business Center, 2100 E. Elliot Rd. Tempe, AZ. Enter the facility through the Main (South) Lobby in building 94 and sign in with Security (*Photo ID required*) **BEFORE 6:00 PM**. You will be escorted to the meeting room. The presentation promptly starts at **6:00 PM**.
Agenda: 5:30–6:00 PM: Social/Refreshments, 6:00–7:00 PM: Presentation, 7:00 PM: Dinner (Pizza and Soda will be provided by the IEEE Phoenix Section CPMT Society Chapter)
IEEE members and non-members are all welcome to attend. **Please arrive at the facility entrance no later than 5:45 PM.**
-

For more information, please contact any of the following CPMT officers:

Vasu Atluri	(480) 227-8411	Rao Bonda	(480) 786-7749	David Dougherty	(480) 413-6923
Huiyang Fei	(480) 552-4966	Vivek Gupta	(480) 734-0266	Bharat Penmecha	(480) 552-2511
Mahesh Shah	(480) 544-9438	Shawn Shi	(480) 929-5614		



SP-COM Phoenix Chapter

Please join our Google Group!

Please join our increasingly popular Google group to get the most up-to-date information about the society's activities. We have now over 50 members who are availing of this facility. Email traffic is thin, and used only to send meeting notices. No spam !

<https://groups.google.com/d/forum/ieee-sp-com-phoenix-chapter>

**In addition, we continue to post meeting notices on IEEE vtools at
(<https://meetings.vtools.ieee.org/main>)**



Phoenix Chapter of the IEEE Computer Society October, 2015

News

Our final chapter meeting of 2015 will be held on Wednesday, December 2nd, at the Phoenix (Central) Campus of the ITT Technical Institute. The campus is located at 10220 N 25th Avenue, Phoenix. The venue is east of the I-17 between Peoria and Dunlap. The speaker will be Mark Goldstein of International Research Corporation. He will speak on the Internet of Things. More details will be published later.

Chapter elections for the 2016 officers will be held at this meeting.

The October meeting featured Schuyler St. Ledger, a young man who has been present at several Computer Society meetings. He spoke on software defined radio.

Visit the CS Chapter website for the latest information: <http://ewh.ieee.org/r6/phoenix/compsociety/>.
For brief announcements regarding upcoming events we are also on Twitter: @IEEECS_PHX

If you would like to suggest a topic or speaker for any of our future meetings, please contact one of the chapter officers:

Chair	Jerry Crow	jerry.crow@computer.org
Vice-chair	Dr. Brad Morantz	bradscientist@ieee.org
Secretary	Audrey Skidmore	askidmore@computer.org
Treasurer	Diane Smith	sdianesmith@computer.org
Webmaster	Audrey Skidmore	askidmore@computer.org



IEEE Power and Energy Society
Phoenix Chapter

<http://www.ewh.ieee.org/soc/pes/phoenix/>



IEEE PES NOVEMBER 2015 LUNCH MEETING – PRINCIPLES AND EVOLUTION OF HV (46 KV OR HIGHER) INSULATED CABLES

WHEN:

November 19, 2015 @ 11:30 am – 1:00 pm

WHERE:

PERA Club
1 E Continental Dr
Tempe, AZ 85281
USA

November 2015 Luncheon Meeting

Date: Thursday, November 19, 2015

Time: 11:30 – 11:45 am: Registration

11:45 am: Lunch

12:00 pm: Program

Location: PERA Club (see location)

Speaker: Mathew Nadakal, VP of Sales, Western region for Marmon Utility LLC (Kerite brand)

Topic: Principles and Evolution of HV (46 kV or higher) insulated cables

Cost: \$8.00 (No cost if you are a college student)

Reservations: Contact Monica at (602) 470-0400 or [click here](#)

Reservations deadline is NOON on Monday, November 16, 2015.

If you have already registered for this luncheon but need to cancel, [click here](#).

Abstract/Overview

- Cable designs and popular configurations.
- HV Cable specifications
- Insulation types, pros and cons
- Voltage stress, corona effect, partial discharge and life expectancy of cables
- Challenges in HV cable installations, splicing and terminations
- Underground vs overhead decisions, dilemmas and economy



WAVES AND DEVICES

PHOENIX CHAPTER

<http://ewh.ieee.org/r6/phoenix/wad/>

2015 Event Calendar



Chapter Chair:

steve.rockwell@ieee.org

Steve Rockwell

Chapter Vice-Chair:

Trevor Thornton t.thornton@asu.edu

<u>Date</u>	<u>Venue</u>	<u>Topic / Title</u>	<u>Speaker</u>	<u>Affiliation</u>	<u>IEEE Society</u>
25-Feb	ASU	Thermal Challenges in Mobile Devices and Potential Solutions	Mulugeta Berhe	Henkel	Electron Devices
26-Feb	ASU	Impact of Be-doping on the material properties of InAs/InAsSb type-II superlattices for infrared detection	Elizabeth Steenberger	Wright-Patterson Air Force Base	Photonics
27-Mar	ASU	Advanced Antenna Systems for Satellite Communication Payloads	Sudhakar Rao	Northrop Grumman	Antennas
20-Apr	ASU	Surface Acoustic Wave Devices – Challenges for Technology Development in Modern Communication Systems	Richard Gruenwald	Vectron	Ultrasonics
22-May	ASU	Microwave and Millimeter Wave Power Amplifiers: Technology, Applications, Benchmarks, and Future Trends	Jim Komiak	BAE	Microwaves
22-May	ASU	Overview of Different Numerical Solvers for Electromagnetic Applications	Felipe Cátedra	Univ. of Alcalá, Madrid, Spain	Antennas
Aug					
23-Sept	ASU	Modern Methods for Microwave Filter Synthesis	Richard Cameron	MTT Dist. Lecturer	Microwaves
Oct	Freescal e	Free Form Flexible-Stretchable-Reconfigurable Electronics: Tomorrow's Applications Today	Muhammad Mustafa Hussain	IEEE EDS Distinguished Lecturer	Electron Devices Society
Nov					

For more information, contact:

Steve Rockwell (WAD Chapter Chair) (480) 241-9891
 Curtis Scott (WAD Chapter Publicity) (623) 703-9177

steve.rockwell@ieee.org
curtiscott@gmail.com



IEEE Phoenix Section Life Member Affinity Group

Technical Presentation, Officer Elections and Administrative Meeting

Meeting December 15, 2015

Program Presentation: Energy Innovations from Concept to Construction

Today's energy market is in the early stages of a transition that will unfold over the next few decades. This transition will require innovation in technology, policy, educational strategies, and the integration and management of technical and social systems involved in the new energy era. In this time we must challenge ourselves to explore the systems-level implications of energy options on technical, economic, behavioral, and environmental metrics, and use that understanding to guide our basic research, technology design, and integration and control to achieve the greatest impact. This requires systems thinking joined with detailed technical and scientific evaluation throughout all stages of the engineering design process.

Dr. Johnson will describe and discuss his research within a larger strategic framework that engages in basic research, systems integration, and deployment of energy innovations from concept to construction across three synergistic areas:

- (1) distributed resource modeling, integration, and control with focus on home energy systems,
- (2) micro-grid design and deployment for on-grid and off-grid applications, and
- (3) off-grid power solutions including solar homes, battery charging stations, and village grids.

Dr. Johnson will also provide educational examples from his in-class and out-of-class activities for training the evolving US energy workforce, and discuss technical initiatives for rural electrification through the IEEE Smart Village, a signature IEEE program.

The Presenter: Dr. Nathan Johnson

Dr. Nathan Johnson is an Assistant Professor in The Polytechnic School of the Ira A. Fulton Schools of Engineering at Arizona State University. He is an active researcher and teacher of sustainable and resilient energy systems. Through his work, Dr. Johnson designs, optimizes, builds, and tests energy innovations to address challenges around the world. This work includes fundamental scientific research and applied engineering projects to help bridge the gap between academic research and commercialization.

Dr. Johnson's research team of 15 people incorporates skillsets from five disciplinary backgrounds. His team actively collaborates with universities, laboratories, industry, and NGOs. Dr. Johnson has been active in IEEE Region 6 through the Global Humanitarian Technology Conference (GHTC) and Rising Stars, and he is recognized by Arizona State University as a Senior Sustainability Scientist in recognition for his globally-focused sustainability efforts.

NOTE MEETING STARTS AT 11 AM

Meeting Agenda:

- 11AM: Attendee introductions
- 11.05 Obtain Lunch
- 11:20 AM: Program Presentation

12:20 Officer's report
12:25 Nominations Accepted for Officers, presentation of Slate
12:30 Officer Elections
12:35 Election results presented
12:45 Admin. Meeting / New Officers

Where: SRP's **PERA Club Bighorn Room,**

1 East Continental Drive, Tempe, AZ

Continental is West of 68th St., ½ mile south of McDowell Road

Enter the Private PERA Club and follow drive to large parking lot. Big Horn is small building at South East corner of lot.

When: Tuesday, **December 15, 2015 - 11:00am – 1:00pm**, Registration fee is \$15. This fee will include lunch provided by the PERA Club.

Lunch: TBD

RSVP: Please advise Ronald Sprague r.sprague@ieee.org if you plan to attend so accounting for lunch is possible.

Technical Presentations: The Program Chairs are seeking suggestion from members for future presentations. Any ideas of interest are open for consideration. Please contact Ronald Sprague or Barry Perlman Program Chairs at r.sprague@ieee.org and/or barry.perlman@gmail.com.

About IEEE Phoenix Section Life Member Affinity Group: The IEEE Phoenix Section Life Member Affinity Group was organized to enable IEEE Life Members to retain active IEEE associations, contribute to the social good in their communities, advance IEEE's professional interests and enjoy each other's company.

Activities: Technical meetings scheduled the 3rd Tuesday of February, May, October, and December. Elections are held at the December meeting.

Future Technical Meetings: All meeting are scheduled at the SRP PERA CLUB. It is suggested you put these dates on your calendar to attend the meetings.

- Tuesday December 15, 2015
- Tuesday February 16, 2016
- Tuesday May 17, 2016
- Tuesday October 18, 2016

Officers:

Chair	Leslie Daviet II	lesdaviatii@cs.com
Vice Chair	Jim Tang	JFTANG@cox.net
Secretary	Tom Lundquist	tom.lundquist@ieee.org
Treasurer	Leslie Daviet II	lesdaviatii@cs.com
Membership Program	Rao Thallam	Rao.Thallam@gmail.com
	Ron Sprague	r.sprague@ieee.org
	Barry Perlman	barry.perlman@gmail.com
Volunteer	Gary Frere	gary.frere@gmail.com
Past Chair	Barry Cummings	abarrycummings@gmail.com



IEEE Phoenix Section News

IEEE Phoenix Section Awards For The Year 2015

The IEEE Phoenix Section recognizes the contributions of members, non-members, society chapters, affinity groups, student branches, corporations, and educational institutions at the annual banquet. The next banquet is scheduled for Saturday, February 13th, 2016 at Hilton Phoenix Airport located at 2435 South 47th Street, Phoenix, AZ – 85034 from 5:30 PM to 9:30 PM (Tel: 480-894-1600).

The Section is pleased to issue a call for nominations for this year's Section awards. The scope and purpose of the Section Awards Program is to plan, promote and implement IEEE award programs that recognize outstanding performance in furthering the objectives and professional aims of the IEEE Phoenix Section, the IEEE, and the IEEE-USA, and to stimulate others to pursue such achievements of excellence.

The Phoenix Section has established the following general award categories:

- Member
- Society Chapter/Affinity Group
- Non-member
- Corporate
- Educational
- Section Chair

The Awards Guide lists the awards along with the selection criteria that will be implemented for selecting the award recipient. The Awards Guide can be accessed at <http://sites.ieee.org/phoenix>.

Please read through the Awards Guide to help you in selecting the award category for nomination.

All sections of the form should be completely filled electronically. Submission of additional documents such as resume in support of the nomination is highly encouraged.

Key dates:

Submission deadline: Sunday, January 3rd, 2016

Awardees and nominators will be informed on: Sunday, January 10th, 2016

Only nomination forms submitted by the deadline will be reviewed by the awards committee consisting of the following IEEE Phoenix Section Officers:

- Awards Committee Chair: Dr. Vasudeva P. Atluri
- Awards Committee Co-Chair: Dr. Charles E. Weitzel
- Past Chair: Ms. Barbara McMinn
- Chair: Mr. Bruce J. Ladewig
- Vice Chair: Mr. Surinder K. Tuli
- Secretary: Mr. Vivek Gupta
- Treasurer: Dr. Mahesh K. Shah
- Student Activities Coordinator: Dr. Diane S. Smith

If you have any additional questions, please contact Dr. Vasudeva P. Atluri, Section Awards Committee Chair, at (480) 227-8411 or by email at vpatluri@ieee.org, and Mr. Bruce J. Ladewig, Section Chair, at (480) 620-9291 or by email at bruceladewig@ieee.org.

IEEE Phoenix Section Student Scholarships For The Year 2015

The IEEE Phoenix Section awards Student Scholarships to full-time graduate and undergraduate students who are IEEE student members. The applying student must attend a university in the Phoenix Section during 2015. The universities include Arizona State University, Arizona State University Polytechnic, DeVry University, Embry-Riddle Aeronautical University, and Northern Arizona University.

The student should submit a completely filled application along with financial aid statement; a one-page personal statement of achievements, interests, and goals; official transcripts of all college work; and recommendation letters. The scholarships are awarded based on academic achievement, financial need, and service to the IEEE.

The IEEE Phoenix Section will present the following Student Scholarship awards at the annual banquet scheduled for Saturday, February 13th, 2016 at Hilton Phoenix Airport located at 2435 South 47th Street, Phoenix, AZ – 85034 from 5:30 PM to 9:30 PM (Tel: 480-894-1600):

“Atluri Award” sponsored by Dr. Vasudeva Prasad Atluri and Dr. Satyavathi Atluri. Total of two award recipients are presented with a plaque and a check for \$1000.00 each. Only graduate students are eligible for these awards.

“AI Gross Award” sponsored by IEEE Components, Packaging, and Manufacturing Technology (CPMT) Society Phoenix Chapter. The award recipient is presented with a plaque and a check for \$1000.00. Graduate and undergraduate students are eligible for this award.

“Irv Kaufman Award” sponsored by IEEE Waves and Devices Phoenix Chapter. The award recipient is presented with a plaque and a check for \$1000.00. Graduate and undergraduate students are eligible for this award.

“Dieter Schroder Award” sponsored by IEEE Phoenix Section. The award recipient is presented with a plaque and a check for \$1000.00. Graduate and undergraduate students are eligible for this award.

The checks for these four awards are given out from the IEEE Phoenix Section Student Scholarship Endowment administered by the IEEE Foundation. To learn more about IEEE Foundation, access <http://www.ieeefoundation.org/>.

Only applications received by the deadline, Friday, January 1st, 2016, will be reviewed by the awards committee consisting of the following IEEE Phoenix Section Officers:

Awards Committee Chair: Dr. Vasudeva P. Atluri
Awards Committee Co-Chair: Dr. Charles E. Weitzel
Past Chair: Ms. Barbara McMinn
Chair: Mr. Bruce J. Ladewig
Vice Chair: Mr. Surinder K. Tuli
Secretary: Mr. Vivek Gupta
Treasurer: Dr. Mahesh K. Shah
Students Activities Coordinator: Dr. S. Diane Smith

Student scholarship winners, upon receiving notification from IEEE Phoenix Section Awards Committee, should send by email completely filled either Form W-9 for US Citizen or Form W-8 for Non-US Resident to Mr. Michael Deering, Director of Development, IEEE Foundation, at m.deering@ieee.org with a copy to Dr. Vasudeva P. Atluri, Section Awards Committee Chair, at vpatluri@ieee.org, by Friday, January 15th, 2016.

Key dates:

Application submission deadline: Friday, January 1st, 2016
Scholarship recipients will be informed on: Monday, January 11th, 2016
Submit W-8 and W-9 Forms by: Friday, January 15th, 2016

If you have any additional questions, please contact Dr. S. Diane Smith, Section Student Activities Coordinator, at (602) 749-4601 or by email at sdianesmith@computer.org, and Dr. Vasudeva P. Atluri, Section Awards Committee Chair, at (480) 227-8411 or by email at vpatluri@ieee.org.

IEEE Phoenix Section Officer Terms

At the November 3, 2015 Executive Committee (ExCom) meeting of the IEEE Phoenix Section officers and representatives of the affiliated Chapters and Affinity Groups, a decision was made to change the term of IEEE Phoenix Section Officers from one year to two years in accordance with the bylaws the Phoenix Section operates under. The rationale of this decision included operational efficiency and effectiveness of individuals being in a position for two years and thus more able to implement improvements; program continuity and planning; and improved section operations.

Per the Phoenix Section website (<http://sites.ieee.org/phoenix/about/section-bylaws/>), the Phoenix Section is “required to operate in accordance with IEEE Constitution, Bylaws, Policies, and the MGA Operations Manual.” Per Section 9.4.F.7.b. of the MGA Operations Manual:

- “The term of office for all officers shall be one or two years. A Section must define the officer term as one or two years and record it in its local operating procedures document; if the officer term is not recorded in the local operating procedures document, it shall be two years. An individual may continue in the position until a successor has been duly elected and takes office.”

There may be times when an individual is unable to serve for two years in a position so annually the Nominating Committee will confirm with each officer their willingness and ability to serve in the specific position for the second year of their term. If someone needs to drop out after their first year or be replaced, the Nominating Committee will identify replacements and place them on the ballot for election. Typically, the officer succession plan is to request individuals serving as officers to progress through the various positions but this is not a requirement.

The purpose of this notice is to record the decision reached regarding Phoenix Section Officers serving two year terms. Please contact any of the Phoenix Section Officers if you have questions or input. Thank you.

Executive Committee Meeting

No meeting of Executive Committee in July & August

Normal meetings are on first Tuesday of the month from 6:00 PM to 8:00 PM
The Airport Hilton Phoenix,
2435 S 47th St. Phoenix, AZ 85034, (480) 894-1600.

2015 Executive Committee

Chair: Bruce Ladewig
Vice Chair: Surinder Tuli
Secretary: Vivek Gupta
Treasurer: Mahesh Shah
Past Chair: Barbara McMinn

Executive Committee Meetings

Date: First Tuesday of every month, except July and August
Time: 6:00 – 8:00 p.m.
Location: Hilton Phoenix Airport, 2435 South 47th Street, Phoenix, AZ 85034


IEEE Senior Member and Fellow Grade

IEEE Phoenix Section Membership Development would like to nominate eligible IEEE Members from the Section to Senior Member and Fellow Grades. Please review the requirements at www.ieee.org for eligibility.

Eligible candidates are requested to send in their resumes to Dr. Vasudeva P. Atluri, Membership Development Coordinator, at ypatluri@ieee.org and Dr. Bruce Ladewig, Section Chair, at bruceladewig@ieee.org for consideration.

Phoenix Section LinkedIn Group


If you are interested in professional networking and shared Section related updates & discussions join the [IEEE Phoenix Section Group on LinkedIn](#). Signing up only takes minutes and is free. A job board is available as well.

You can also go to IEEE Phoenix Section LinkedIn page by clicking  button on the [IEEE Phoenix Section home page](#)

IEEE Phoenix Section Ventures into Social Media

You can access the web page three ways:

Use the URL: <https://www.facebook.com/IEEEPhoenixSection>

Click on the Facebook logo  link from [IEEE Phoenix section home page](#).

Search for IEEE Phoenix Section from your Facebook page.

We need following help.

1. Each of you access the IEEE Phoenix Section Web page and click on "Like" hyperlink.
2. Go on the Friends section of the page and "Invite Your Friends." Once you click on Invite button, it will get your email contact list. Your facebook contact list will already be populated with your Facebook friends and you can simply click the Invite button next to their name. Please invite as many friends as you can.
3. Provide me the contents for posting on a regular basis - meeting/ event announcements, Event pictures, Videos.
4. Start some discussion topics under - Status section.

IEEE Membership Grade Advancement

IEEE Phoenix Section Executive Committee encourages all to apply for advancement in membership grade to Senior Member and Fellow Grade. Please review the requirements at www.ieee.org. Please contact IEEE Phoenix Section Membership Development Chair, Dr. Vasudeva P. Atluri, at vpatluri@ieee.org for additional information.

Enhanced Senior Member Application Launched

Effective 29 July 2011, IEEE Admission and Advancement launched a [new Senior Member Application](#). The new application includes numerous enhancements, based on feedback from volunteers and members, including:

- New user friendly format / design
- Secure environment (need IEEE Web account)
- Ability to save application in “draft” form
- Ability to upload resume or Curriculum Vitae (up to 3 MB)
- Applicant can view application online
- Applicant can view status of requested reference forms
- References will be notified by email to provide applicant reference
- References will have the ability to view their completed reference form(s)
- Real time application status

The goal is to provide prospective Senior Members with an easy to use and intuitive interface, while streamlining internal operations at the same time. [View the new Senior Member application](#).

IEEE Member's Benefits



Connect with other technology professionals

Collaborating with a community that shares similar interests can help you take your career to the next level. That's why we created IEEE Collabratec, an online community where technology professionals are networking, collaborating, and creating globally. Here's some of what you can do on IEEE Collabratec:

- Participate in discussions with other professionals.
- Access interactive communities like these:



- Cloud Computing, Big Data, Transportation Electrification, Internet of Things, All-Society Tech Forum
- Technology networks in Africa, Asia/Pacific, Europe, Middle East, North America, and South America
- Women in Leadership, IEEE Young Professionals, IEEE Author Lab, IEEEExtreme, IEEE Day, CareersConnect-USA
- Create Private Groups for research projects or to organize activities.

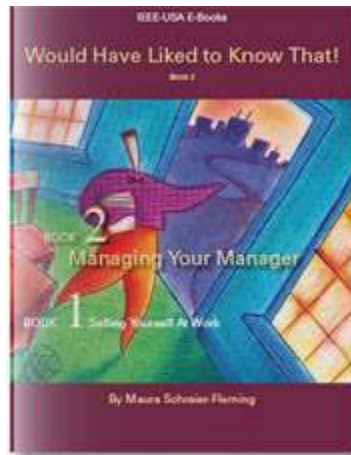
Free IEEE-USA eBook Offered as Special Benefit to IEEE Members

As a special benefit of IEEE Membership through 15 November, IEEE-USA is offering a free eBook, ***Would Have Liked to Know That! Book 2: Managing your Manager***, by Maura Schreier-Fleming.

Managing your Manager Book 2 of this series, Schreier-Fleming writes that managers give clues about how you should work with them. She outlines what those clues are, and also helps you develop effective persuasion strategies for working with your manager. According to Schreier-Fleming, the ultimate goal is to be more productive, have less stress, and be more likely to get what you want, as you work with your manager.

Schreier-Fleming explores many clues that will help you make a decision about the person you are analyzing - from handshakes to facial expressions and body language. Other topics in *Managing the Manager* include:

- How To Build Rapport
- Determine Your Manager's Style
- How To Manage Your Manager: Expressive
- How To Manage Your Manager: Driver
- How to Manage Your Manager: Analytical
- How To Manage Your Manager: Amiable



Members can download *Managing the Manager* for free through 15 November 2015. Sign in with your IEEE Account, add the book to your Cart, and enter the promo code **OCTFREE** at checkout.

In November, the IEEE-USA free eBook will be *The Best of Today's Engineer: On Licensure - Volume 1*, compiled by Georgia C. Stelluto. This free eBook is a compilation of articles that will help the reader understand why one should pursue licensure; the licensure process; exam development and how to effectively study for and pass the licensure exams.

Member Discounts

GetInsured

Did you know that as an IEEE member, you now have access to Mercer Marketplace* powered by GetInsured? Mercer Marketplace is the easiest way to shop for health insurance. It also offers a wealth of entertaining, educational content to help you understand your options.

As an IEEE member, you have the freedom to compare available plans and secure a solution that strikes the best balance between coverage and affordability. Plus, you can do this **confidentially and conveniently in minutes**. You pay no additional cost to take advantage of this service.

2016 Open Enrollment for health insurance starts soon! [Learn more about the Mercer Marketplace powered by GetInsured.](#)

* Provided by Mercer Health & Benefits LLC

These individual health insurance plans are not sponsored by IEEE nor the Mercer Marketplace. Available in the United States.

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That is why we are pleased to let you know that you have access to My Financial Wellness for IEEE Members, a new program available in the US.

Whether you are well along your financial plan or had some bumps along the way, you still can benefit from financial planning. At My Financial Wellness for IEEE Members, you can benefit from no-cost educational resources, financial tools, and credentialed financial advisors to help you get your financial plans in shape.

To learn more, visit IEEEFinancialWellness.com.



IEEE-USA Webinars

Date Revisions for some IEEE-USA Webinars

IEEE-USA has had to reschedule the webinar [From Page to Stage](#) originally planned to take place in October. This webinar will now take place on 19 November at 2:00pm EST. IEEE-USA has partnered with the [IEEE Professional Communication Society](#) to address a topic that has confounded everyone from students to professionals at one time or another. *From Page to Stage* will discuss how to take the written version of your work from its form in a lab notebook, a report, or a paper and translate it into a presentation or poster. Dr. Julia M. Williams is Executive Director of the Office of Institutional Research, Planning, and Assessment and Professor of English at Rose-Hulman Institute of Technology and the presenter for this webinar. She will offer a clear process for making this transition successfully and she will provide concrete strategies for making the most effective use of presentations. [If you haven't registered for this webinar you still have time!](#)

Leadership

IEEE-USA has revised its upcoming webinars on leadership. Elizabeth Lions, who earlier this year provided three great webinar presentations on the topic of leadership, will return this fall to IEEE-USA with one more webinar presentation on the topic of leadership and a webinar on emotional intelligence. [Situational Leadership](#) is the key to driving teams from being adequate to spectacular. Situations will arise in the office, but as a leader it's your responsibility to get the team headed in the right direction. [Emotional Intelligence](#) is the ability to monitor one's own and other people's emotions to discriminate between different emotions and label them appropriately, and to use emotional information to guide thinking and behavior. Elizabeth will explain what emotional intelligence is, why it's important and how to develop the skill. Situational Leadership and Emotional Intelligence will take place on Friday 13 November and 11 December from 1:00pm 2:00pm EST. Again, you can register for both of these webinars

today at the [IEEE-USA website](#).



[Introducing the Kalman Filter](#)

This tutorial is a guide to how the Kalman Filter works. Dr. Ramsey Faragher explains that even students without a strong mathematical background can understand what the Kalman Filter can do to smooth measurements and fuse data together.



[AuthorLab: Information on the IEEE article processing charges](#)

This video describes the payment options offered by IEEE to pay Article Processing Charges.



[SIMD Programming in VOLK, the Vector-Optimized Library of Kernels](#)

To improve the speed of signal processing and computation, Tom Rondeau, Nick McCarthy, and Tim O'Shea walk through the VOLK (Vector Optimized Library of Kernels) library for SIMD (Single Instruction Multiple Data) Programming.

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Refer a Colleague, Get Great Merchandise!

In conjunction with IEEE-USA, IEEE is excited to continue this special offer for US members. Refer a colleague to IEEE. If they join before the end of the membership year, they'll get a 50% discount off their first year membership, and you'll get a gift. IEEE-USA gift items you can choose from include:

- Cooler backpack
- Portable solar battery charger
- Portable speaker
- Parker ballpoint pen
- Golf balls
- Golf umbrella

- Computer backpack
- Tablet case
- Parker pen and mechanical pencil set
- Travel coffee mug and tumbler set
- Baseball hat
- Travel umbrella

Members remain eligible to receive incentives through the existing IEEE Member-Get-a-Member (MGM) program. How it works:

- Refer your colleague via the [online form](#).
- Your referral will receive an email inviting them to join at a 50% discount off first-year membership dues, and will receive benefits through 31 December 2017.
- Your referral will provide your IEEE member number when he or she joins.
- Within 1-2 weeks after your referral joins, you will receive an email confirming your recruiting success, including a link which allows you to select your IEEE-USA merchandise item.
- You will receive a separate email for each new member you recruit.

Please help spread the word and share your IEEE experience - no one knows how beneficial IEEE Membership is to technical and career development better than you, the member. [Refer your friends and colleagues today!](#)

IEEE Mentoring Program

IEEE MentorCentre is the online mentoring platform for IEEE. This is a valuable resource for IEEE members seeking a professional mentoring partnership. That means all the best practices you have come to expect from an IEEE mentoring program are in place, with ample opportunity to enter a unique mentoring partnership not found anywhere else.



What you will find with IEEE MentorCentre:

- The ability to connect with mentors based on specialized areas of practice, experience, IEEE societal affiliation and more
- Opportunities to give back to the profession by registering as a mentor
- Additional fields to narrow down the preferred profile of the mentor
- Improved mentor controls allowing you to control how you are viewed in the system

Participation in the program is voluntary and open to all IEEE members above the grade of Student member.

[Access IEEE MentorCentre](#)

IEEE ResumeLab

IEEE members have a powerful tool to help gain a competitive edge in the employment process. IEEE ResumeLab is an online service that allows IEEE members to develop a resume *occurriculum*



vitae using specialized tools tailored for each step of the job seeking process. This product is added to the list of offerings that assist members as they find jobs and develop their careers.

IEEE ResumeLab is designed with a series of modules that assist the member through the employment process. Key modules and features include:

- **Resumes** - Select from a wide array of templates geared toward specific industries, sectors and work experience stages.
- **Letters** - From cover letter to post-interview thank you letter, ensure optimal communication throughout the hiring process.
- **Skills Assessment** - Highlight the skills you possess, your competency in those skills, and what makes your experience with these skills unique.
- **Mock Interviews** - Prepare for the real thing by selecting an interviewer and the type of questions they'll ask. Choose to record your interview for evaluation and feedback.
- **Video Resumes** - Record custom video messages for potential employers.
- **Portfolios** - Upload and organize your past work to present to potential employers.
- **Share Online** Publish and share everything you create on a publicly viewable website.

[Access IEEE ResumeLab](#)

Call for Nominations: IEEE Technical Field Awards

Nominations are due 31 January annually for the IEEE Technical Field Awards (TFA). IEEE TFAs are awarded for contributions or leadership in a specific field of interest of IEEE and are among the highest awards presented on behalf of the IEEE Board of Directors.

All IEEE members are encouraged to submit a nomination for a worthy candidate within their technical fields. Nomination forms and award-specific criteria can be [downloaded](#).

Since 1917, the IEEE Awards Program has paid tribute to technical professionals whose exceptional achievements and outstanding contributions have made a lasting impact on technology, society, the engineering profession, and humanity. By this means, the image and prestige of the organization, its members, and the profession are all enhanced.

For more information visit the [Awards program](#) online or email awards@ieee.org.



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